

2010

GreenMil International

Quality Team

[PCB COMPONENT CREATION CHECKLIST]

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Date:

New PCB Component Creation Checklist

| | | | | | |
|------------------------|---|-------------|--|--------------------|--|
| Component Name: | | Type | | Board Name: | |
| Part No. | | | | Created By: | |
| Make | | | | Verified By | |
| Sl. No. | Description | | | | |
| 1. | Check the orientation of the component with the datasheet. Ensure that the component is created with the view from Top. | | | | |
| 2. | Check the Dimensions of the created components with the datasheet. | | | | |
| 3. | Check if the Pad drill hole diameters/slots are as per datasheet. | | | | |
| 4. | Check if sufficient pad area is provided for soldering | | | | |
| 5. | For QFN Packages (having thermal Pads) check if Vias have been provided on the thermal pads for connectivity to plane. | | | | |
| 6. | For BGA's check if a 'no component placement' area of 100mils surrounding the BGA is provided on the component side. | | | | |
| 7. | Check if local fiducials have been provided for fine pitch components. | | | | |
| 8. | Check if a placement boundary of 15 – 25 mils more wrt component outline has been provided. (keep out from other components) | | | | |
| 9. | Check if both silkscreen outline and assembly outline have been provided. | | | | |
| 10. | Check if polarity markings have been provided if the component is polarized. | | | | |



| | | |
|-----|---|--|
| 11. | Check if direction markings have been provided for right angled connectors/switches/components which are to be accessed from outside. | |
| 12. | Check if pin no./names have been provided on the silkscreen and assembly for components having pin count > 2. | |
| 13. | Check if the Pin no./names provided on the silkscreen and assembly are correct. | |
| 14. | Check if thermal pads and anti pads have been provided in the inner layers for through hole components. | |
| 15. | Check if solder mask opening of minimum 5 mils have been provided for all the pads | |
| 16. | Check if solder mask openings have been provided on both the solder and component side for through hole pads. | |
| 17. | Check if solder paste pads equal to the pad size have been provided for all smd pads. | |
| 18. | Check if the dimensions of the components have been marked on the 'dimension' layer (in mils). | |
| 19. | Check if the names of the pads used are entered in the 'pad_stack_name' subclass layer | |
| 20. | | |

Checked By

Verified By

Date:

Date: